

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01196	100.0	0.25513
			Subtotal	0.01196	100	0.25513
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.04218	90.0	0.9
	Tin alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00023	0.5	0.005
	Tin alloy	Silver (Ag)	7440-22-4	0.00117	2.5	0.025
	Tin alloy	Antimony (Sb)	7440-36-0	0.00328	7.0	0.07
			Subtotal	0.04686	100	1
Die	Doped silicon	Silicon (Si)	7440-21-3	0.29528	100.0	6.3
			Subtotal	0.29528	100	6.3
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.1875	100.0	4.00047
			Subtotal	0.1875	100	4.00047
Heat Spreader	Copper alloy	Phosphorous (P)	7723-14-0	0.01687	0.03	0.36
	Copper alloy	Iron (Fe)	7439-89-6	0.05624	0.1	1.2
	Copper alloy	Copper (Cu)	7440-50-8	56.17102	99.87	1198.44
			Subtotal	56.24413	100	1200
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.26549	100.0	27
			Subtotal	1.26549	100	27
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00562	0.03	0.12
	Copper alloy	Iron (Fe)	7439-89-6	0.01875	0.1	0.4
	Copper alloy	Copper (Cu)	7440-50-8	18.72367	99.87	399.48
			Subtotal	18.74804	100	400
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.05859	5.0	1.25
	Lead alloy	Silver (Ag)	7440-22-4	0.02929	2.5	0.625
	Lead alloy	Lead (Pb)	7439-92-1	1.08387	92.5	23.125
			Subtotal	1.17175	100	25
Isolator	Copper alloy	Phosphorous (P)	7723-14-0	0.00422	0.1	0.09
	Copper alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.86397	91.6	82.44
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.03796	0.9	0.81
	Copper alloy	Molybdenum (Mo)	7439-98-7	0.29528	7.0	6.3
	Copper alloy	Manganese (Mn)	7439-96-5	0.01687	0.4	0.36
			Subtotal	4.2183	100	90
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.26716	1.5	5.7
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	1.69201	9.5	36.1
	Filler	Silica fused	60676-86-0	15.67337	88.0	334.4
	Carbon Black	Carbon black	1333-86-4	0.17811	1.0	3.8
			Subtotal	17.81065	100	380
			Total	99.99996	100	2133.5556

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